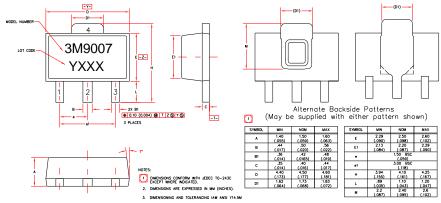


## **Mechanical Information**

## **Package Information and Dimensions**

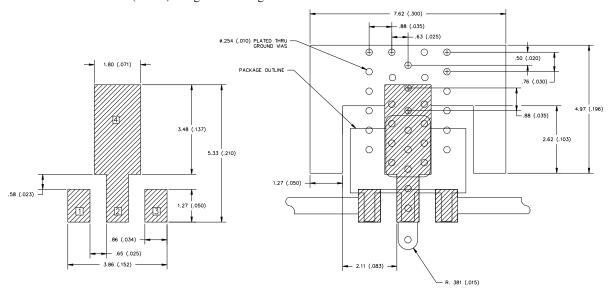
This package is lead-free/RoHS-compliant. The plating material on the leads is NiPdAu. It is compatible with both lead-free (maximum 260 °C reflow temperature) and lead (maximum 245 °C reflow temperature) soldering processes.

The component will be marked with a "3M9007" designator with an alphanumeric lot code on the top surface of package. The "Y" represents the last digit of the year the part was manufactured; the "XXX" is an auto generated number.



## **Mounting Configuration**

All dimensions are in millimeters (inches). Angles are in degrees.



## Notes:

- 1. Ground / thermal vias are critical for the proper performance of this device. Vias should use a .35mm (#80 / .0135") diameter drill and have a final plated thru diameter of .25 mm (.010").
- 2. Add as much copper as possible to inner and outer layers near the part to ensure optimal thermal performance.
- 3. RF trace width depends upon the PC board material and construction.
- 4. Use 1 oz. Copper minimum.

Data Sheet: Rev B 04/01/11 © 2010 TriQuint Semiconductor, Inc.

Disclaimer: Subject to change without notice

Connecting the Digital World to the Global Network®

-8 of 9 -